

# INTERNATIONAL STANDARD

# NORME INTERNATIONALE



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**Field device integration (FDI) –  
Part 5: Information Model**

**Intégration des appareils de terrain (FDI) –  
Partie 5: Modèle d'Information**



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Part 5: Information Model**

**Intégration des appareils de terrain (FDI) –  
Partie 5: Modèle d'Information**

INTERNATIONAL  
ELECTROTECHNICAL  
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International Standard IEC 62769-5 has been prepared by subcommittee 65E: Devices and integration in enterprise systems, of IEC technical committee 65: Industrial-process measurement, control and automation.

This second edition cancels and replaces the first edition published in 2015. This edition constitutes a technical revision.

This edition includes the following significant technical changes with respect to the previous edition:

- a) support for generic protocol extension for faster adoption of other technologies;
- b) support of new protocols;
- c) generic protocol extension to allow adoption of other communication protocols;
- d) based on generic protocol extension: Modbus RTU.

The text of this International Standard is based on the following documents:

FDIS	Report on voting
65E/762/FDIS	65E/772/RVD

Full information on the voting for the approval of this International Standard can be found in the report on voting indicated in the above table.

This document has been drafted in accordance with the ISO/IEC Directives, Part 2.

A list of all parts in the IEC 62769 series, published under the general title *Field Device Integration (FDI)*, can be found on the IEC website.

This standard contains attached files in the form of XML schema. These files are intended to be used as a complement and do not form an integral part of the standard.

The committee has decided that the contents of this document will remain unchanged until the stability date indicated on the IEC website under "<http://webstore.iec.ch>" in the data related to the specific document. At this date, the document will be

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## INTRODUCTION

The IEC 62769 series has the general title *Field Device Integration (FDI)* and the following parts:

- Part 1: Overview
- Part 2: FDI Client
- Part 3: FDI Server
- Part 4: FDI Packages
- Part 5: FDI Information Model
- Part 6: FDI Technology Mapping
- Part 7: FDI Communication Devices
- Part 100: Profiles – Generic Protocol Extensions
- Part 101-1: Profiles – Foundation Fieldbus H1
- Part 101-2: Profiles – Foundation Fieldbus HSE
- Part 103-1: Profiles – PROFIBUS
- Part 103-4: Profiles – PROFINET
- Part 109-1: Profiles – HART and WirelessHART
- Part 115-2: Profiles – Protocol-specific Definitions for Modbus RTU
- Part 150-1: Profiles – ISA 100.11a

# FIELD DEVICE INTEGRATION (FDI) – Part 5: Information Model

## 1 Scope

This part of IEC 62769 defines the FDI Information Model. One of the main tasks of the Information Model is to reflect the topology of the automation system. Therefore, it represents the devices of the automation system as well as the connecting communication networks including their properties, relationships, and the operations that can be performed on them. The types in the AddressSpace of the FDI Server constitute a catalogue, which is built from *FDI Packages*.

The fundamental types for the FDI Information Model are well defined in OPC UA for Devices (IEC 62541-100). The FDI Information Model specifies extensions for a few special cases and otherwise explains how these types are used and how the contents are built from elements of DevicePackages.

The overall FDI architecture is illustrated in Figure 1. The architectural components that are within the scope of this document have been highlighted in this illustration.

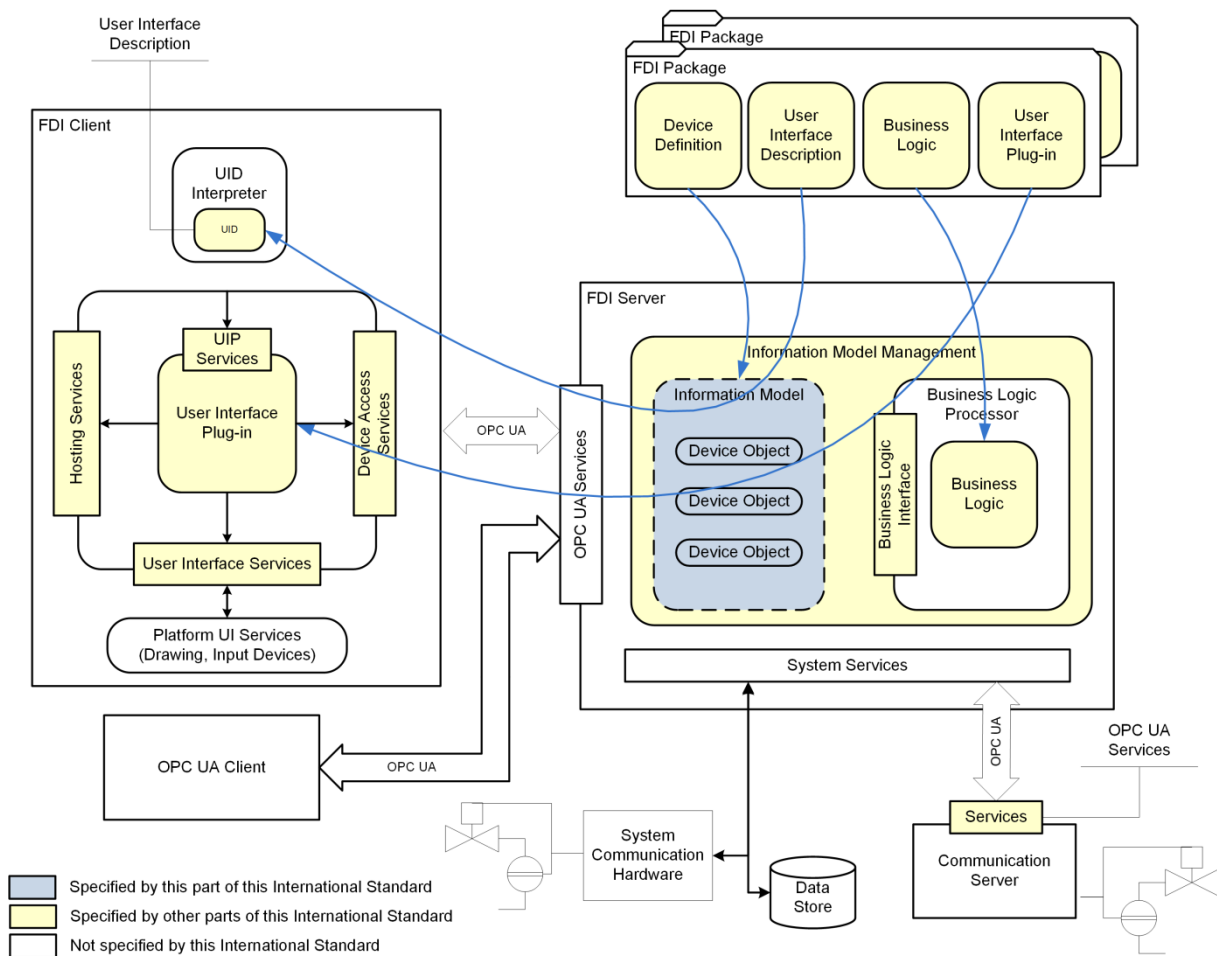


Figure 1 – FDI architecture diagram